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To Be AssignedGroup Art Unit
To Be AssignedInvention: **CHEMICALLY AMPLIFIED POSITIVE PHOTOSENSITIVE RESIN COMPOSITION**I hereby certify that this **English Language abstract of JP 62-215947 - 2 Pages**
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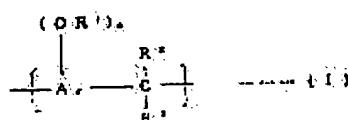
(54) PHOTORESISTIVE COMPOSITION AND PHOTORESISTIVE LITHOGRAPHIC
PRINTING PLATE

(57)Abstract:

PURPOSE: To obtain a material for a lithographic printing plate having superior photosensitivity without deteriorating the developability or the suitability to exposure giving a visible image by forming a photosensitive layer contg. a compound producing an acid by exposure and a prescribed compound on a support.

CONSTITUTION: A photosensitive layer of a photosensitive composition contg. a compound producing an acid by exposure and a compound having at least three acetal bonds which are decomposed by the acid in the molecule is formed on a support. Novolak resin represented by formula I (where Ar is an aromatic group, R1 is 2-cyclic ether, each of R2 and R3 is H, alkyl

or phenyl and n≥3) may be used as the compound having at least three acetal bonds in the molecule. The about of the compound used is 20W80wt%, preferably 50W60wt%



of the total amount of the solid substances in the photosensitive composition. An alkali-soluble resin such as cresol-formaldehyde resin or phenol-cresol formaldehyde resin may be added to the composition.

LEGAL STATUS

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